

T-6000-L

TRESKY's entry-level model, DIE bonder **T-6000-L**, is a fully automatic placement system for universal and specific use in prototyping as well as series production.

The **T-6000-L** offers an unprecedented level of flexibility through a high degree of modularity. Fast switching between different bonding techniques is possible at any time and the manual mode enables fast bonding results without programming.



For a customized bonding result, the **T-6000-L** can be equipped with numerous options that can be added to the placement process at any time.

The **T-6000-L** guarantees reproducible and highly accurate results for any placement application and best bonding performance in the market. The unique manual mode enables instant DIE bonding.

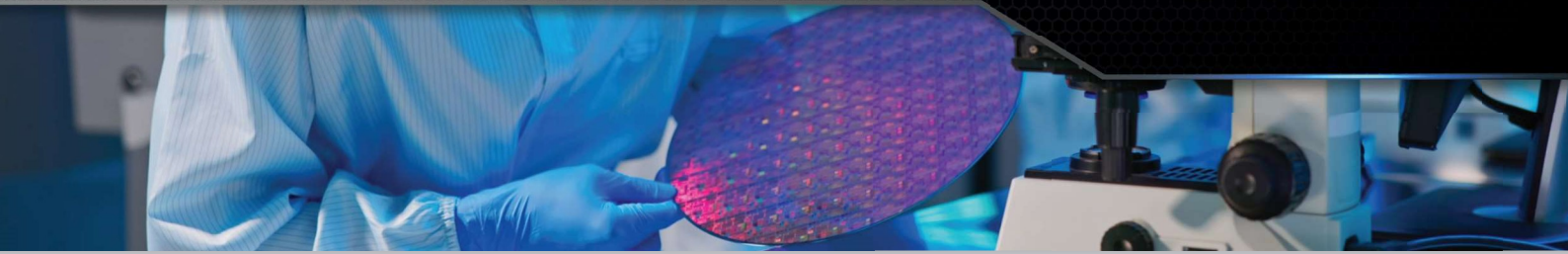
This model covers all common bonding technologies and is designed to meet today's and tomorrow's challenges in semiconductor manufacturing.

Technical Data

Travel Range with Wafer	400 mm x 410 mm
Wafer Size	2" - 8" (Ring & Frame)
Travel Range w/o Wafer	540 mm x 410 mm
Z-Movement	100 mm
Chip Rotation Max.	up to 360°
Bond Force Range	0.01 - up to 100 N *
Axis Speed	up to 1.8 m/sec
Placement Accuracy	8 µm @ 3 sigma
Axis Resolution	XYZ: 0.01 µm, theta: 0.01°
Min./Max. Comp. Size	0.05 mm - 100 mm **

* Higher bond forces on request

** Other dimensions on request | Note:
All specifications are subject to change
without prior notice



Product Highlights

- Best ROI in the market
- Manual mode
- Multichip capable
- Post-bond inspection
- Software programmed temperature control
- Wafermapping
- OCR
- Traceability
- MES
- Automated dispensing needle calibration
- Scrubbing
- Bonding in cavities (15 mm)
- Preform punching



more information

Modules & Options

- Wafer table with DIE ejector
- UV indexer
- WRGB ring light
- Heating plates
- Up to 450 °C
- ΔT ramps up to 60 K/s
- Inert gas
- Automatic tool change
- Various dispensing technologies
- Stamping unit
- Tool heating
- Various feeder widths
- Uplooking camera
- ID scanner
- DIE flipping unit
- Heated inert gas
- Automatic wafer change
- Magazine feeder
- Inline production
- Formic Acid Module

Bonding Solutions

- Epoxy Bonder
- UV Bonder
- Ultrasonic Bonder
- Thermocompression Bonder
- Sinter Bonder
- Flip Chip Bonder
- Eutectic Bonder
- 3D Bonder

Applications

- Micro assembly
- Eutectic bonding
- Stamping
- Ultrasonic bonding
- Flip chip bonding
- Thermosonic bonding
- Thermocompression bonding
- Flux dipping
- Epoxy bonding
- DIE stacking

Customized applications

- DTF / DAF bonding
- Multi-DIE bonding
- MEMS
- SMD bonding
- 3D packaging (SiP)
- Laser bar stacking
- Glass bonding
- TO header bonding
- RFID assembly
- DIE sorting

For more information about our products
or services please visit our website.

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